

# Stanford

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## Bill Yen

Ph.D. Student in Electrical Engineering, admitted Autumn 2023

 Curriculum Vitae available Online

### Bio

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#### BIO

Bill Yen is a Ph.D. student in the Department of Electrical Engineering at Stanford University working in the area of low-power Internet of Things (IoT) systems. He is an interdisciplinary maker and environmental scientist passionate about solving issues related to food, water, and energy using smart technologies.

Yen's experience in industry (General Motors, CNH Industrial) and academic research (Northwestern - soil-powered computing, Stanford - low-power wireless communication) cultivated his interest in designing self-powered computing devices that boost system efficiency while lowering the environmental impact of existing processes. His work has been featured by The Independent, MIT Technology Review China, Hackster.io, and more. He is also a recipient of the Stanford Graduate Fellowship in Science & Engineering.

#### HONORS AND AWARDS

- Ovid W. Eshbach Award, Northwestern University (June 2023)
- Stanford Graduate Fellowship in Science & Engineering, Stanford University (September 2023)

#### EDUCATION AND CERTIFICATIONS

- Bachelor of Science, Northwestern University , Mechanical Engineering (2023)
- Minor, Northwestern University , Environmental Engineering (2023)
- Segal Design Certificate, Northwestern University (2023)
- LEED AP BD+C, U.S. Green Building Council (2020)

#### LINKS

- Personal Website: <https://billyen33.com>
- LinkedIn: <https://www.linkedin.com/in/bill-yen/>

### Research & Scholarship

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#### LAB AFFILIATIONS

- Zerina Kapetanovic (9/25/2023)

### Publications

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#### PUBLICATIONS

- **Soil-Powered Computing: The Engineer's Guide to Practical Soil Microbial Fuel Cell Design** *Proceedings of the ACM on Interactive, Mobile, Wearable and Ubiquitous Technologies*

Yen, B., Jaliff, L., Gutierrez, L., Sahinidis, P., Bernstein, S., Madden, J., Taylor, S., Josephson, C., Pannuto, P., Shuai, W., Wells, G., Arora, N., Hester, et al  
2024; 7 (4): 1-40